

## **ABSTRACT**

### **CUTTING APPARATUS**

A cutting apparatus includes a width measuring unit for measuring the width of a grooving groove formed in a wafer by laser grooving and the width of a cut groove formed by a cutting blade. The width measuring unit includes an imaging camera for imaging the grooving groove and the cut groove, and an illuminating unit for illuminating an area to be imaged by the imaging camera with light supplied in a predetermined light quantity. Therefore, when first light is radiated from the illuminating unit, a first image in which the grooving groove is sharply imaged can be imaged by the imaging camera, whereas when second light is radiated from the illuminating unit, a second image in which the cut groove is clearly imaged can be imaged by the imaging camera. Consequently, the grooving groove and the cut groove can be easily distinguished from each other.

(Figure 1)